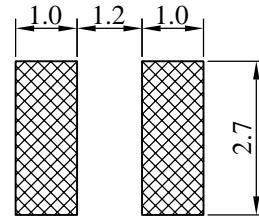
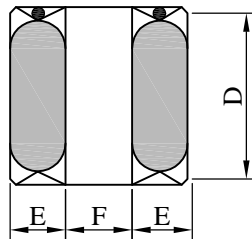
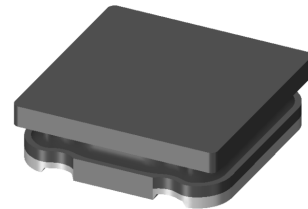
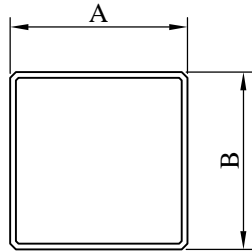


SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.	SN3010□□□□L□-□□□		
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I . Configuration and dimensions :



(PCB Pattern)

Unit : m/m

A	B	C	D	E	F
3.00 ±0.1	3.00 ±0.1	1.00 max.	2.70 typ.	0.90 ±0.2	1.20 ±0.2

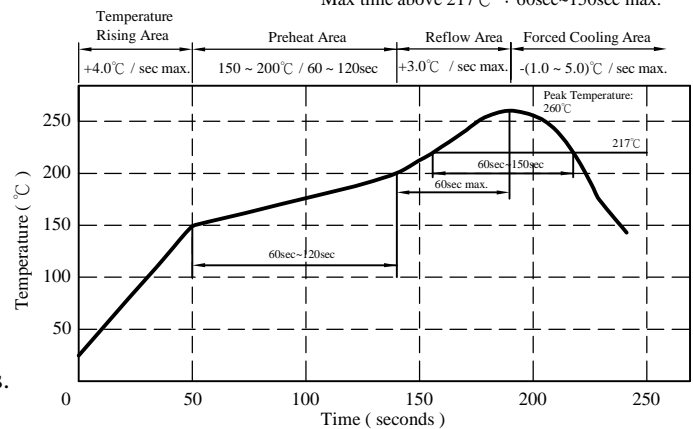
II . Description :

- a . Ferrite drum core construction.
- b . Magnetically epoxy.
- c . Enamelled copper wire : H class
- d . Product weight : 0.032g (ref.)
- e . Moisture sensitivity Level 1
- f . Products comply with RoHS' requirements
- g . Halogen free available

III . General specification :

- a . Storage Temp. : -40°C ----+85°C
- b . Operating Temp. : -40°C----+125°C
(Temp. rise included)
- c . Resistance To Solder Heat : 260°C.10 Secs.

Peak Temp : 260°C max.
Max. Peak Temp - 5°C : 30sec max.
Max time above 217°C : 60sec~150sec max.



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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.	SN3010□□□□L□-□□□		
		REV.	20150722-E	PAGE	2

IV . Electrical characteristics :

DWG No.	Inductance @0.1V/1MHz (μ H)	RDC (Ω)		SRF (MHz) min.	Irms (A) typ.	Isat (A) typ.
		typ.	max.			
SN30101R0YL□-□□□	1.0 \pm 30%	0.065	0.078	180	1.700	1.950
SN30101R5YL□-□□□	1.5 \pm 30%	0.080	0.096	140	1.650	1.600
SN30102R2ML□-□□□	2.2 \pm 20%	0.095	0.114	100	1.450	1.450
SN30103R3ML□-□□□	3.3 \pm 20%	0.160	0.192	80	1.300	1.050
SN30104R7ML□-□□□	4.7 \pm 20%	0.190	0.228	60	1.100	0.950
SN30106R8ML□-□□□	6.8 \pm 20%	0.300	0.360	50	0.850	0.760
SN3010100ML□-□□□	10.0 \pm 20%	0.450	0.540	45	0.720	0.610
SN3010150ML□-□□□	15.0 \pm 20%	0.740	0.888	35	0.560	0.480
SN3010220ML□-□□□	22.0 \pm 20%	0.980	1.176	25	0.500	0.420
SN3010330ML□-□□□	33.0 \pm 20%	1.550	1.860	24	0.415	0.340
SN3010470ML□-□□□	47.0 \pm 20%	2.000	2.400	19	0.320	0.270

- 1). □ : Packaging information : □ Code
- 2). "-□□□" : Reference code
- 3). Electrical specifications at 25°C
- 4). Isat base on $\Delta L/L0A=30\%$ typ.
- 5). Irms base on Temp. rise 40°C typ.

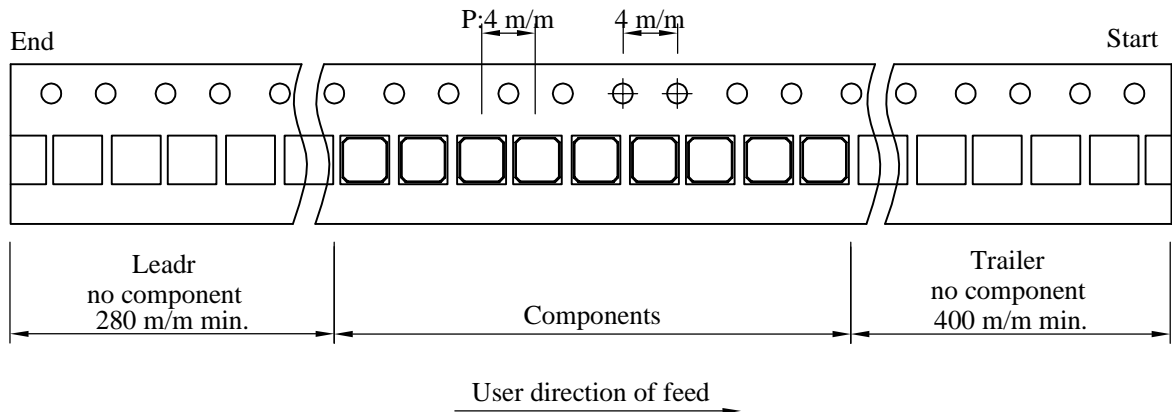
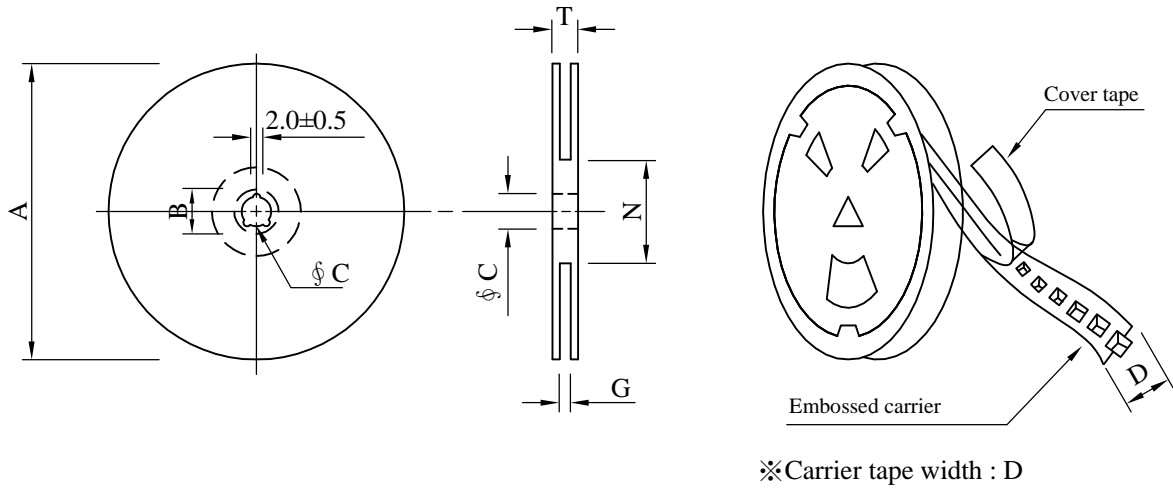
SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.		SN3010□□□□L□-□□□	
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V . Packaging information :

(1) Configuration



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	2,000	500	07 - 08	80,000	17.5	42 x 41 x 24

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SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Semi-shielded SMD Power Inductor	ABC'S DWG NO.	SN3010□□□□L□-□□□		
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VI . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 85±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +85℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature : 85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in appearance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitud : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature : 260±5℃. 2.Time (temp. ≥ 217℃) : 60~150 Second. 3.IR reflow times : 3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 30% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ typ.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing : 150±5℃ / 16Hours±30 min. 2.Peak temperature : 240±5℃ 3.Time (temp. ≥ 217℃) : 60~150 second. 4.IR reflow times : 1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40℃~125℃ 2.Room temperature : 25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time : 6 time (Every side of sample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.

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